TITLE: METHOD FOR PRODUCTION OF SEMICONDUCTOR PACKAGE

ABSTRACT OF DISCLOSURE

The invention provides a method for producing semiconductor packages comprising the steps of forming electronic circuits for a plurality of semiconductor chips 11 on a wafer 1, forming bumps 2 on the plurality of semiconductor chips 11, encapsulating the circuit-forming surface 111 of the wafer 1 and the bumps 2 with a sealant by screen printing means to form a sealant layer 4, curing the sealant layer 4, grinding the surface of the sealant layer 4 until the upper end surface of the bump 2 becomes exposed, placing solder balls on said upper end surface of bumps 2 to weld the balls to the surface thereof, and dicing the wafer 1 and the sealant layer 4 as united into individual semiconductor chips 11. Screen printing means is used to encapsulate the entire surface of the wafer with a resin, so that the equipment costs can be markedly reduced as compared with conventional methods using a mold.

FIG 2